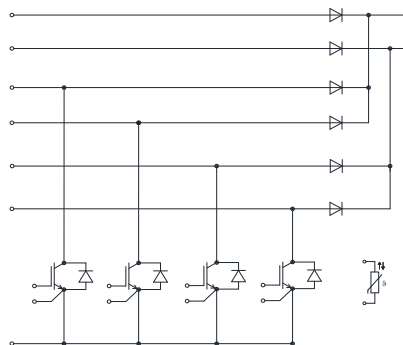
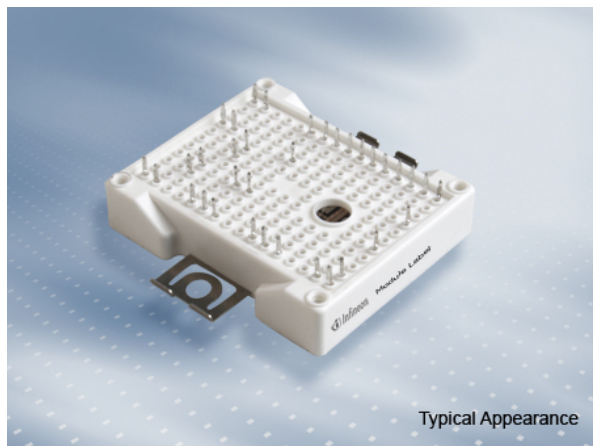


EasyPACK モジュール and PressFIT / NTCサーミスタ
 EasyPACK module and PressFIT / NTC



$V_{CES} = 1200V$
 $I_{C\ nom} = 160A / I_{CRM} = 320A$

一般応用

- ソーラーアプリケーション

電気的特性

- 高速IGBT H3
- 低スイッチング損失
- thinQ!_H SiC ショットキーdiode 1200V

機械的特性

- 3 kV AC 1分 絶縁耐圧
- 低熱インピーダンスの Al₂O₃ DCB
- 内蔵されたNTCサーミスタ
- コンパクトデザイン
- PressFIT 接合 技術

Typical Applications

- Solar applications

Electrical Features

- CoolSiC (TM) Schottky diode gen 5
- High speed IGBT H3
- Low switching losses
- thinQ!_H SiC Schottky diode 1200V

Mechanical Features

- 3 kV AC 1min insulation
- Al₂O₃ substrate with low thermal resistance
- Integrated NTC temperature sensor
- Compact design
- PressFIT contact technology

Module Label Code

Barcode Code 128



DMX - Code



Content of the Code

Content of the Code	Digit
Module Serial Number	1 - 5
Module Material Number	6 - 11
Production Order Number	12 - 19
Datecode (Production Year)	20 - 21
Datecode (Production Week)	22 - 23

バイパスダイオード / Bypass-Diode

最大定格 / Maximum Rated Values

ピーク繰返し逆電圧 Repetitive peak reverse voltage	$T_{vj} = 25^{\circ}\text{C}$	V_{RRM}	1200	V
最大実効順電流/chip Maximum RMS forward current per chip	$T_H = 60^{\circ}\text{C}$	I_{FRMSM}	50	A
整流出力の最大実効電流 Maximum RMS current at rectifier output	$T_H = 60^{\circ}\text{C}$	I_{RMSM}	60	A
サージ順電流 Surge forward current	$t_p = 10\text{ ms}, T_{vj} = 25^{\circ}\text{C}$ $t_p = 10\text{ ms}, T_{vj} = 150^{\circ}\text{C}$	I_{FSM}	450 360	A A
電流二乗時間積 I^2t - value	$t_p = 10\text{ ms}, T_{vj} = 25^{\circ}\text{C}$ $t_p = 10\text{ ms}, T_{vj} = 150^{\circ}\text{C}$	I^2t	1000 650	A^2s A^2s

電気的特性 / Characteristic Values

		min. typ. max.			
順電圧 Forward voltage	$T_{vj} = 150^{\circ}\text{C}, I_F = 30\text{ A}$	V_F		0,95	V
逆電流 Reverse current	$T_{vj} = 150^{\circ}\text{C}, V_R = 1200\text{ V}$	I_R		0,10	mA
ジャンクション・ヒートシンク間熱抵抗 Thermal resistance, junction to heatsink	/Diode (1 素子当り) / per diode	R_{thJH}		1,60	K/W
動作温度 Temperature under switching conditions		$T_{vj\text{ op}}$	-40		150 $^{\circ}\text{C}$

逆極性保護diodeA / Inverse-polarity protection diode A

最大定格 / Maximum Rated Values

ピーク繰返し逆電圧 Repetitive peak reverse voltage	$T_{vj} = 25^{\circ}\text{C}$	V_{RRM}	1200	V
最大実効順電流/chip Maximum RMS forward current per chip	$T_H = 100^{\circ}\text{C}$	I_{FRMSM}	30	A
整流出力の最大実効電流 Maximum RMS current at rectifier output	$T_H = 100^{\circ}\text{C}$	I_{RMSM}	60	A
サージ順電流 Surge forward current	$t_p = 10\text{ ms}, T_{vj} = 25^{\circ}\text{C}$ $t_p = 10\text{ ms}, T_{vj} = 150^{\circ}\text{C}$	I_{FSM}	290 245	A A
電流二乗時間積 I^2t - value	$t_p = 10\text{ ms}, T_{vj} = 25^{\circ}\text{C}$ $t_p = 10\text{ ms}, T_{vj} = 150^{\circ}\text{C}$	I^2t	420 300	A^2s A^2s

電気的特性 / Characteristic Values

		min. typ. max.			
順電圧 Forward voltage	$T_{vj} = 150^{\circ}\text{C}, I_F = 20\text{ A}$	V_F		1,00	V
逆電流 Reverse current	$T_{vj} = 150^{\circ}\text{C}, V_R = 1200\text{ V}$	I_R		0,10	mA
ジャンクション・ヒートシンク間熱抵抗 Thermal resistance, junction to heatsink	/Diode (1 素子当り) / per diode	R_{thJH}		2,35	K/W
動作温度 Temperature under switching conditions		$T_{vj\text{ op}}$	-40		150 $^{\circ}\text{C}$

IGBT、チヨッパー / IGBT-Chopper

最大定格 / Maximum Rated Values

コレクタ・エミッタ間電圧 Collector-emitter voltage	$T_{vj} = 25^{\circ}\text{C}$	V_{CES}	1200	V
コレクタ電流 Implemented collector current		I_{CN}	40	A
連続DCコレクタ電流 Continuous DC collector current	$T_H = 100^{\circ}\text{C}, T_{vj\max} = 175^{\circ}\text{C}$	$I_{C\text{nom}}$	20	A
繰り返しピークコレクタ電流 Repetitive peak collector current	$t_p = 1\text{ms}$	I_{CRM}	80	A
ゲート・エミッタ間ピーク電圧 Gate-emitter peak voltage		V_{GES}	+/-20	V

電気的特性 / Characteristic Values

		min.	typ.	max.	
コレクタ・エミッタ間飽和電圧 Collector-emitter saturation voltage	$I_C = 20\text{A}, V_{GE} = 15\text{V}$ $I_C = 20\text{A}, V_{GE} = 15\text{V}$ $I_C = 20\text{A}, V_{GE} = 15\text{V}$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	$V_{CE\text{sat}}$	1,55 1,70 1,75	1,70 V V V
ゲート・エミッタ間しきい値電圧 Gate threshold voltage	$I_C = 1,00\text{mA}, V_{CE} = V_{GE}, T_{vj} = 25^{\circ}\text{C}$		$V_{G\text{Eth}}$	5,00 5,80 6,50	V
ゲート電荷量 Gate charge	$V_{GE} = -15\text{V} \dots +15\text{V}$		Q_G	0,32	μC
内蔵ゲート抵抗 Internal gate resistor	$T_{vj} = 25^{\circ}\text{C}$		$R_{G\text{int}}$	0,0	Ω
入力容量 Input capacitance	$f = 1\text{MHz}, T_{vj} = 25^{\circ}\text{C}, V_{CE} = 25\text{V}, V_{GE} = 0\text{V}$		C_{ies}	2,35	nF
帰還容量 Reverse transfer capacitance	$f = 1\text{MHz}, T_{vj} = 25^{\circ}\text{C}, V_{CE} = 25\text{V}, V_{GE} = 0\text{V}$		C_{res}	0,13	nF
コレクタ・エミッタ間遮断電流 Collector-emitter cut-off current	$V_{CE} = 1200\text{V}, V_{GE} = 0\text{V}, T_{vj} = 25^{\circ}\text{C}$		I_{CES}		1,0 mA
ゲート・エミッタ間漏れ電流 Gate-emitter leakage current	$V_{CE} = 0\text{V}, V_{GE} = 20\text{V}, T_{vj} = 25^{\circ}\text{C}$		I_{GES}		100 nA
ターンオン遅れ時間 (誘導負荷) Turn-on delay time, inductive load	$I_C = 20\text{A}, V_{CE} = 600\text{V}$ $V_{GE} = \pm 15\text{V}$ $R_{G\text{on}} = 12\Omega$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	$t_{d\text{on}}$	0,025 0,025 0,028	μs μs μs
ターンオン上昇時間 (誘導負荷) Rise time, inductive load	$I_C = 20\text{A}, V_{CE} = 600\text{V}$ $V_{GE} = \pm 15\text{V}$ $R_{G\text{on}} = 12\Omega$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	t_r	0,01 0,012 0,012	μs μs μs
ターンオフ遅れ時間 (誘導負荷) Turn-off delay time, inductive load	$I_C = 20\text{A}, V_{CE} = 600\text{V}$ $V_{GE} = \pm 15\text{V}$ $R_{G\text{off}} = 12\Omega$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	$t_{d\text{off}}$	0,25 0,32 0,35	μs μs μs
ターンオフ下降時間 (誘導負荷) Fall time, inductive load	$I_C = 20\text{A}, V_{CE} = 600\text{V}$ $V_{GE} = \pm 15\text{V}$ $R_{G\text{off}} = 12\Omega$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	t_f	0,016 0,023 0,025	μs μs μs
ターンオンスイッチング損失 Turn-on energy loss per pulse	$I_C = 20\text{A}, V_{CE} = 600\text{V}, L_S = 30\text{nH}$ $V_{GE} = \pm 15\text{V}, di/dt = 1800\text{A}/\mu\text{s} (T_{vj} = 150^{\circ}\text{C})$ $R_{G\text{on}} = 12\Omega$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	E_{on}	0,26 0,32 0,35	mJ mJ mJ
ターンオフスイッチング損失 Turn-off energy loss per pulse	$I_C = 20\text{A}, V_{CE} = 600\text{V}, L_S = 30\text{nH}$ $V_{GE} = \pm 15\text{V}, du/dt = 3000\text{V}/\mu\text{s} (T_{vj} = 150^{\circ}\text{C})$ $R_{G\text{off}} = 12\Omega$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	E_{off}	0,80 1,20 1,40	mJ mJ mJ
短絡電流 SC data	$V_{GE} \leq 15\text{V}, V_{CC} = 800\text{V}$ $V_{CE\text{max}} = V_{CES} - L_{SCE} \cdot di/dt$ $t_p \leq 10\mu\text{s}, T_{vj} = 150^{\circ}\text{C}$		I_{SC}	130	A
ジャンクション・ヒートシンク間熱抵抗 Thermal resistance, junction to heatsink	IGBT部 (1素子当り) / per IGBT		$R_{th\text{JH}}$	1,10	K/W
動作温度 Temperature under switching conditions			$T_{vj\text{op}}$	-40	150 $^{\circ}\text{C}$

Diode-、チヨツパー / Diode-Chopper

最大定格 / Maximum Rated Values

ピーク繰返し逆電圧 Repetitive peak reverse voltage	$T_{vj} = 25^{\circ}\text{C}$	V_{RRM}	1200	V
連続DC電流 Continuous DC forward current		I_F	15	A
ピーク繰返し順電流 Repetitive peak forward current	$t_P = 1 \text{ ms}$	I_{FRM}	30	A
電流二乗時間積 I^2t - value	$V_R = 0 \text{ V}, t_P = 10 \text{ ms}, T_{vj} = 125^{\circ}\text{C}$	I^2t	40,0	A^2s

電気的特性 / Characteristic Values

			min.	typ.	max.	
順電圧 Forward voltage	$I_F = 15 \text{ A}, V_{GE} = 0 \text{ V}$	$T_{vj} = 25^{\circ}\text{C}$		1,45	1,75	V
	$I_F = 15 \text{ A}, V_{GE} = 0 \text{ V}$	$T_{vj} = 125^{\circ}\text{C}$	V_F	1,75		V
	$I_F = 15 \text{ A}, V_{GE} = 0 \text{ V}$	$T_{vj} = 150^{\circ}\text{C}$		1,85		V
ピーク逆回復電流 Peak reverse recovery current	$I_F = 15 \text{ A}, -di_F/dt = 1800 \text{ A}/\mu\text{s} (T_{vj}=150^{\circ}\text{C})$ $V_R = 600 \text{ V}$	$T_{vj} = 25^{\circ}\text{C}$		5,00		A
		$T_{vj} = 125^{\circ}\text{C}$	I_{RM}	5,00		A
		$T_{vj} = 150^{\circ}\text{C}$		5,00		A
逆回復電荷量 Recovered charge	$I_F = 15 \text{ A}, -di_F/dt = 1800 \text{ A}/\mu\text{s} (T_{vj}=150^{\circ}\text{C})$ $V_R = 600 \text{ V}$	$T_{vj} = 25^{\circ}\text{C}$		0,15		μC
		$T_{vj} = 125^{\circ}\text{C}$	Q_r	0,25		μC
		$T_{vj} = 150^{\circ}\text{C}$		0,25		μC
逆回復損失 Reverse recovery energy	$I_F = 15 \text{ A}, -di_F/dt = 1800 \text{ A}/\mu\text{s} (T_{vj}=150^{\circ}\text{C})$ $V_R = 600 \text{ V}$	$T_{vj} = 25^{\circ}\text{C}$		0,03		mJ
		$T_{vj} = 125^{\circ}\text{C}$	E_{rec}	0,03		mJ
		$T_{vj} = 150^{\circ}\text{C}$		0,03		mJ
ジャンクション・ヒートシンク間熱抵抗 Thermal resistance, junction to heatsink	/Diode (1 素子当り) / per diode	R_{thJH}		1,57		K/W
動作温度 Temperature under switching conditions		$T_{vj op}$	-40		150	$^{\circ}\text{C}$

NTC-サーミスタ / NTC-Thermistor

電気的特性 / Characteristic Values

			min.	typ.	max.	
定格抵抗値 Rated resistance	$T_{NTC} = 25^{\circ}\text{C}$	R_{25}		5,00		k Ω
R100の偏差 Deviation of R100	$T_{NTC} = 100^{\circ}\text{C}, R_{100} = 493 \Omega$	$\Delta R/R$	-5		5	%
損失 Power dissipation	$T_{NTC} = 25^{\circ}\text{C}$	P_{25}			20,0	mW
B-定数 B-value	$R_2 = R_{25} \exp [B_{25/50}(1/T_2 - 1/(298,15 \text{ K}))]$	$B_{25/50}$		3375		K
B-定数 B-value	$R_2 = R_{25} \exp [B_{25/80}(1/T_2 - 1/(298,15 \text{ K}))]$	$B_{25/80}$		3411		K
B-定数 B-value	$R_2 = R_{25} \exp [B_{25/100}(1/T_2 - 1/(298,15 \text{ K}))]$	$B_{25/100}$		3433		K

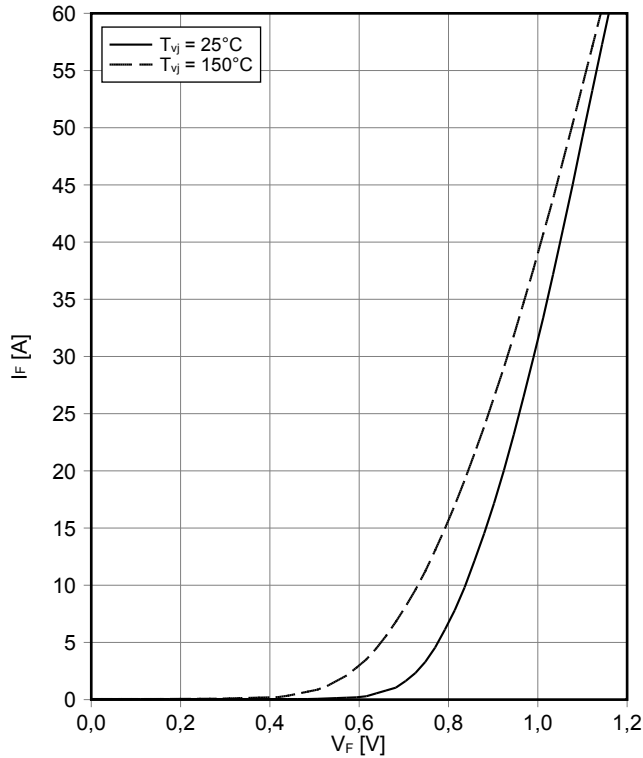
適切なアプリケーションノートによる仕様
Specification according to the valid application note.

モジュール / Module

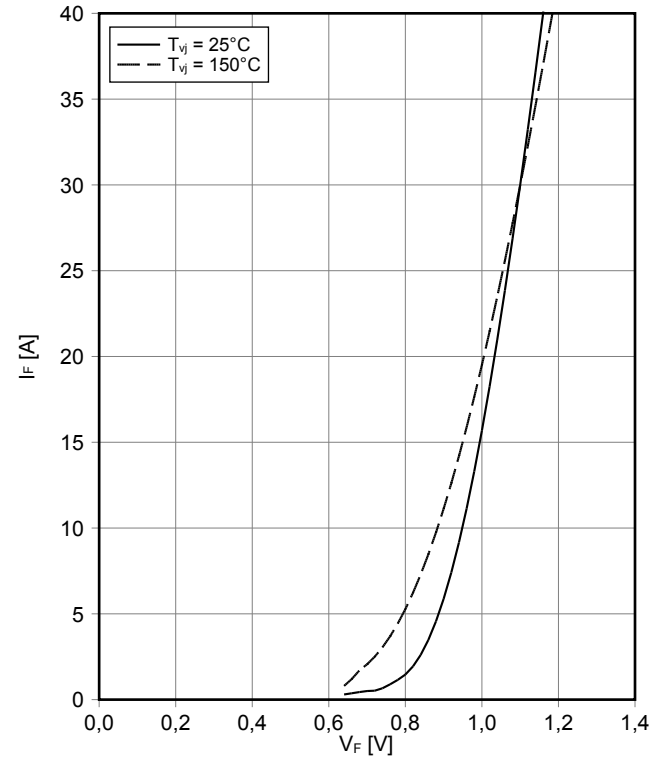
絶縁耐圧 Isolation test voltage	RMS, f = 50 Hz, t = 1 min.	V _{ISOL}	3,0			kV
内部絶縁 Internal isolation	基礎絶縁 (クラス1, IEC 61140) basic insulation (class 1, IEC 61140)		Al ₂ O ₃			
沿面距離 Creepage distance	連絡方法 - ヒートシンク / terminal to heatsink 連絡方法 - 連絡方法 / terminal to terminal		11,5 6,3			mm
空間距離 Clearance	連絡方法 - ヒートシンク / terminal to heatsink 連絡方法 - 連絡方法 / terminal to terminal		10,0 5,0			mm
相対トラッキング指数 Comperative tracking index		CTI	> 200			
			min. typ. max.			
内部インダクタンス Stray inductance module		L _{sCE}		20		nH
保存温度 Storage temperature		T _{stg}	-40		125	°C
Anpresskraft für mech. Bef. pro Feder mounting force per clamp		F	40	-	80	N
質量 Weight		G		36		g

Der Strom im Dauerbetrieb ist auf 25A effektiv pro Anschlusspin begrenzt
The current under continuous operation is limited to 25A rms per connector pin.

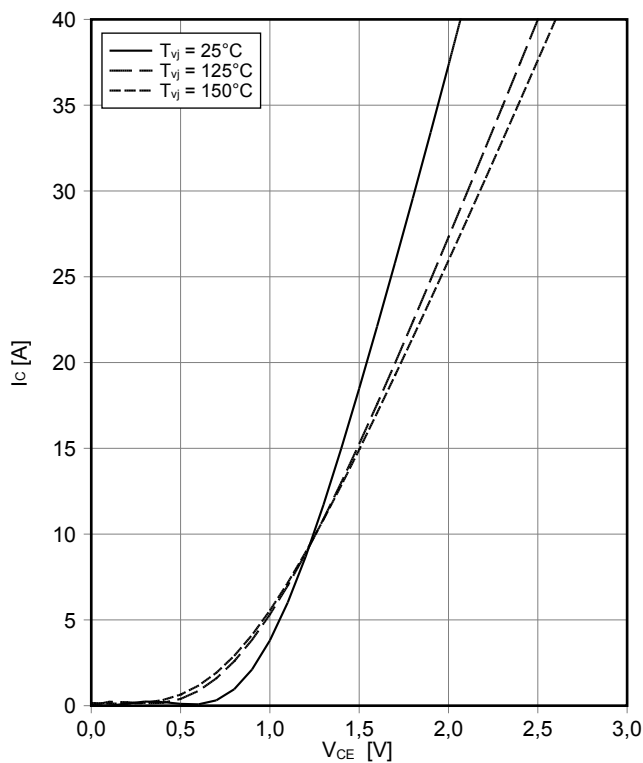
順方向特性 バイパスダイオード (典型)
 forward characteristic of Bypass-Diode (typical)
 $I_F = f(V_F)$



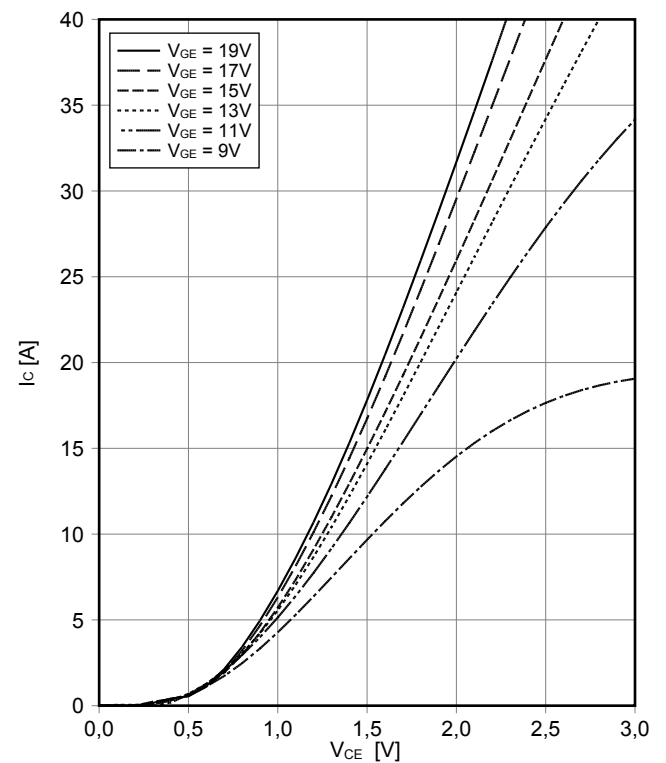
順方向特性 逆極性保護diodeA (典型)
 forward characteristic of Inverse-polarity protection diode A (typical)
 $I_F = f(V_F)$



出力特性 IGBT、チヨツパー (Typical)
 output characteristic IGBT-Chopper (typical)
 $I_C = f(V_{CE})$
 $V_{GE} = 15\text{ V}$

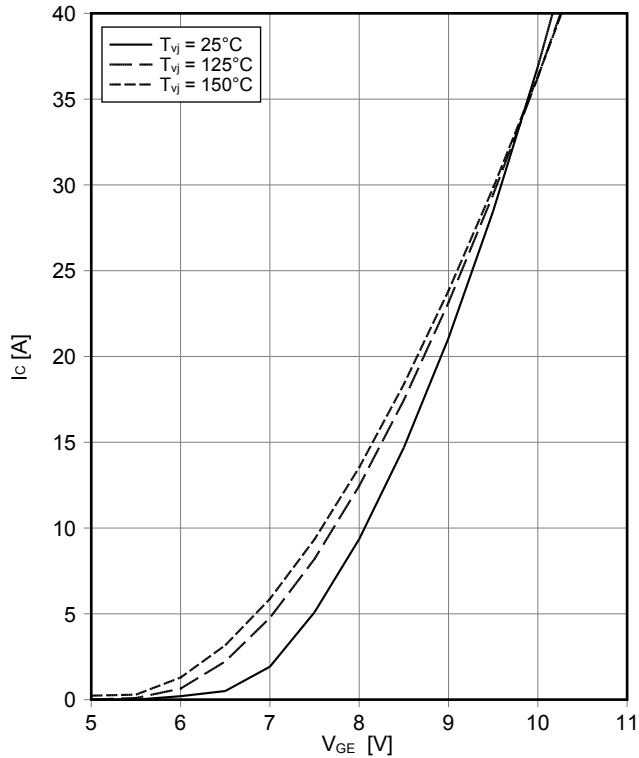


出力特性 IGBT、チヨツパー (Typical)
 output characteristic IGBT-Chopper (typical)
 $I_C = f(V_{CE})$
 $T_{vj} = 150^\circ\text{C}$



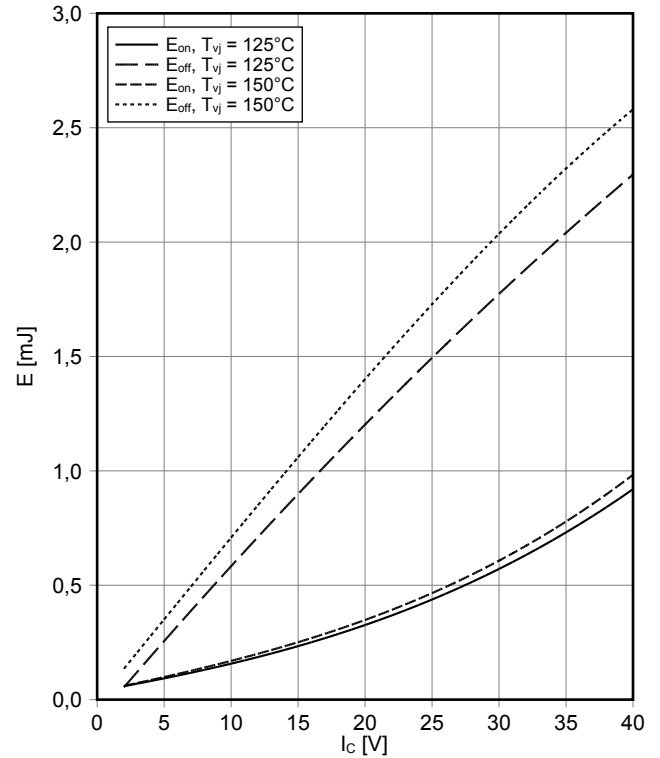
伝達特性 IGBT、チョッパー (Typical)
transfer characteristic IGBT-Chopper (typical)

$I_C = f(V_{GE})$
 $V_{CE} = 20\text{ V}$



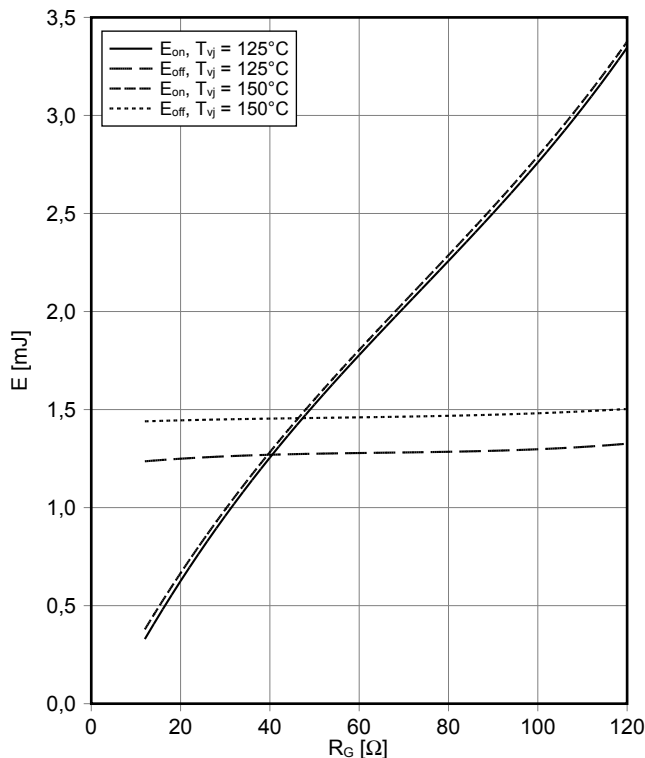
スイッチング損失 IGBT、チョッパー (Typical)
switching losses IGBT-Chopper (typical)

$E_{on} = f(I_C), E_{off} = f(I_C)$
 $V_{GE} = \pm 15\text{ V}, R_{Gon} = 12\ \Omega, R_{Goff} = 12\ \Omega, V_{CE} = 600\text{ V}$



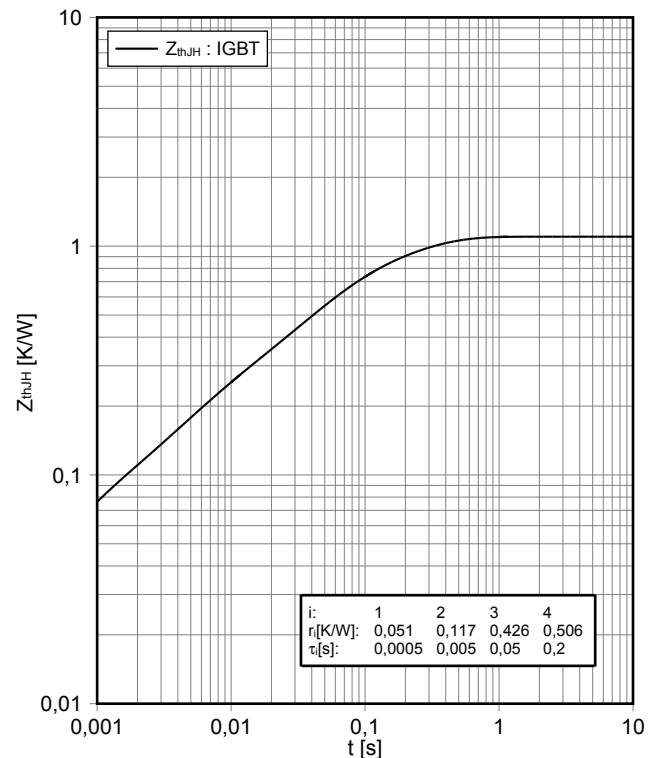
スイッチング損失 IGBT、チョッパー (Typical)
switching losses IGBT-Chopper (typical)

$E_{on} = f(R_G), E_{off} = f(R_G)$
 $V_{GE} = \pm 15\text{ V}, I_C = 20\text{ A}, V_{CE} = 600\text{ V}$



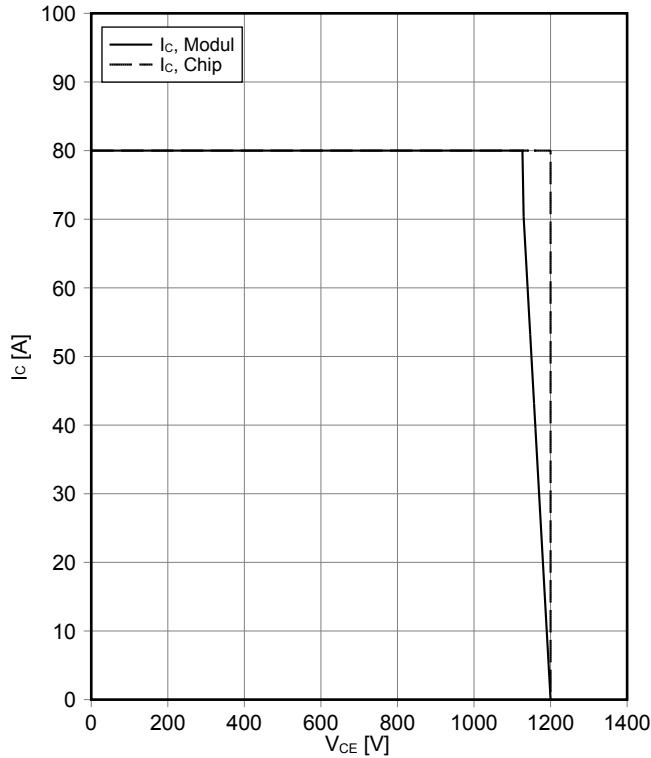
過渡熱インピーダンス IGBT、チョッパー
transient thermal impedance IGBT-Chopper

$Z_{thJH} = f(t)$



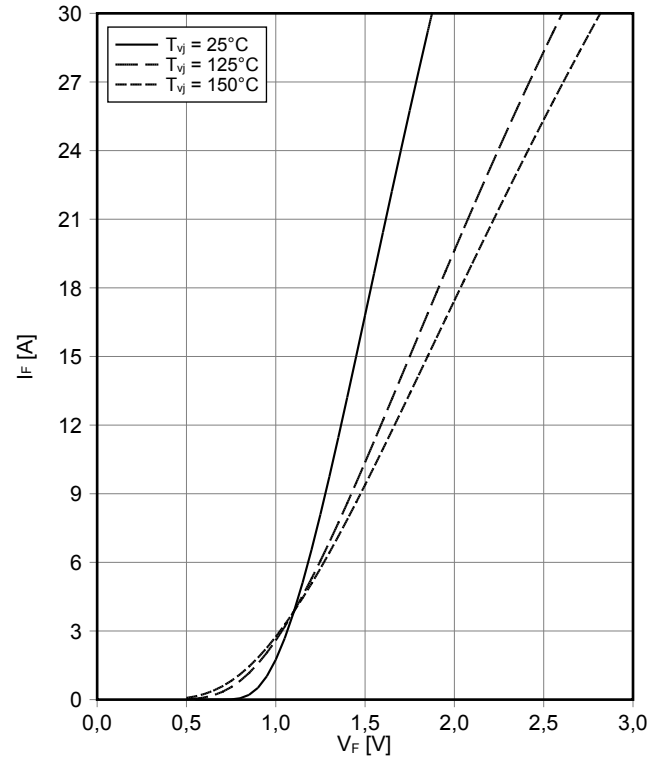
**逆バイアス安全動作領域 IGBT、チヨッパ- (RBSOA)
reverse bias safe operating area IGBT-Chopper (RBSOA)**

$I_C = f(V_{CE})$
 $V_{GE} = \pm 15\text{ V}$, $R_{Goff} = 12\ \Omega$, $T_{vj} = 150^\circ\text{C}$



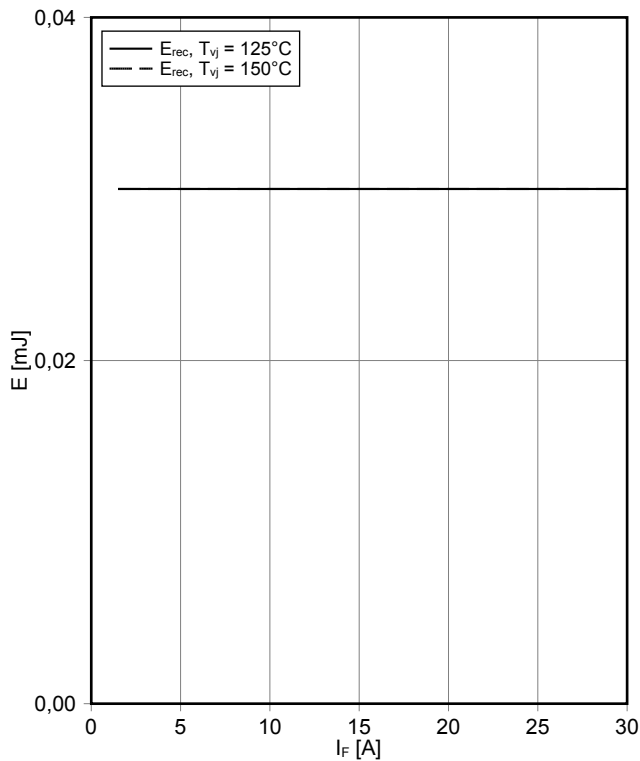
**順電圧特性 Diode-、チヨッパ- (typical)
forward characteristic of Diode-Chopper (typical)**

$I_F = f(V_F)$



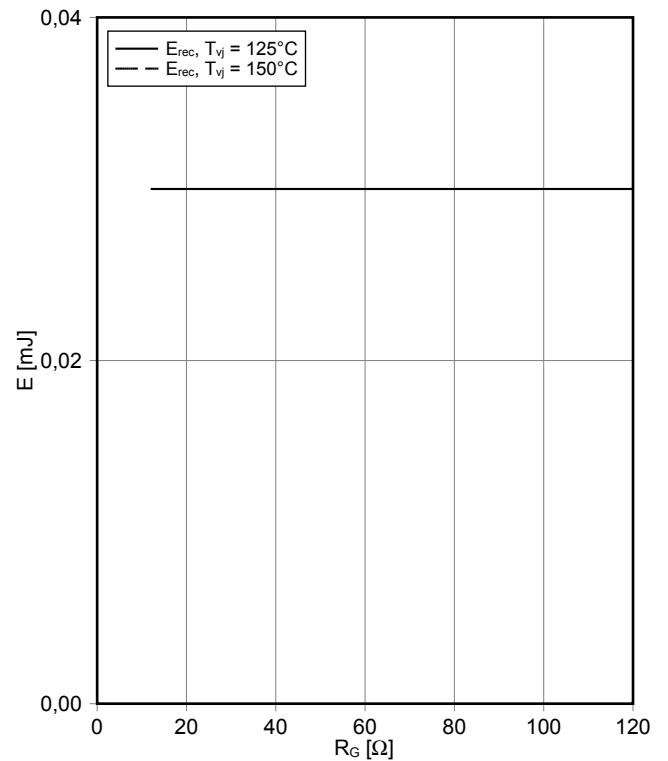
**スイッチング損失 Diode-、チヨッパ- (Typical)
switching losses Diode-Chopper (typical)**

$E_{rec} = f(I_F)$
 $R_{Gon} = 12\ \Omega$, $V_{CE} = 600\text{ V}$

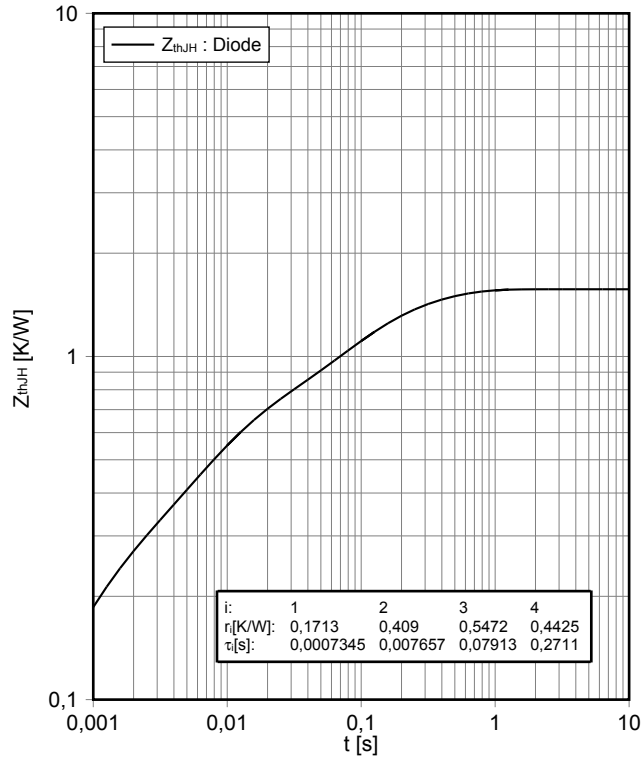


**スイッチング損失 Diode-、チヨッパ- (Typical)
switching losses Diode-Chopper (typical)**

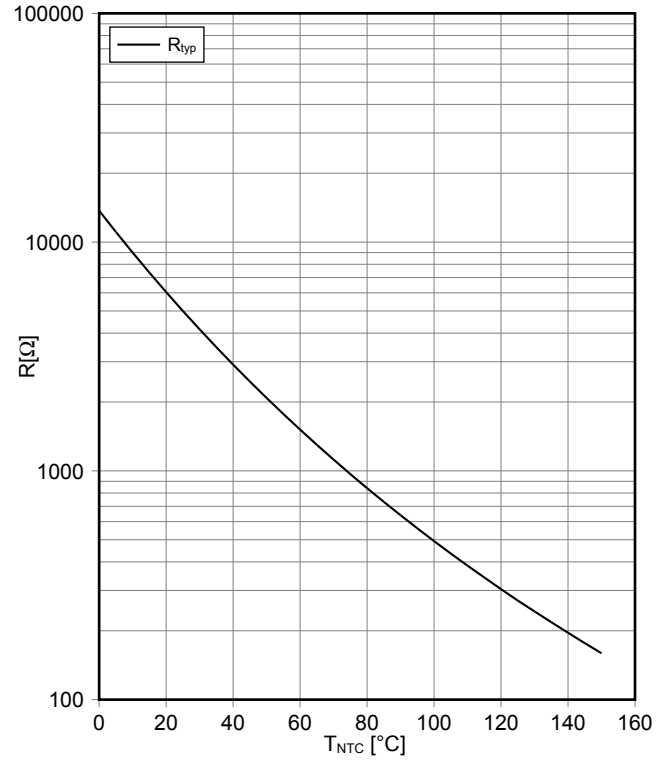
$E_{rec} = f(R_G)$
 $I_F = 15\text{ A}$, $V_{CE} = 600\text{ V}$



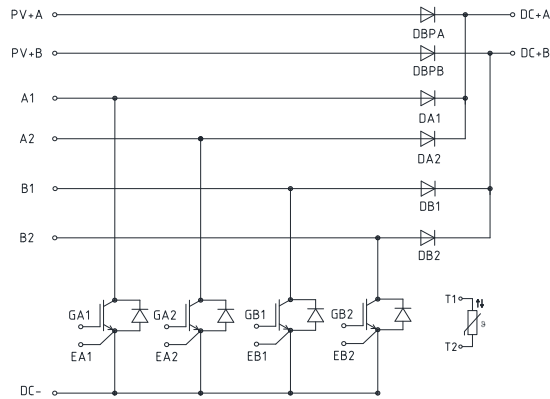
過渡熱インピーダンス Diode-, チョッパー
 transient thermal impedance Diode-Chopper
 $Z_{thJH} = f(t)$



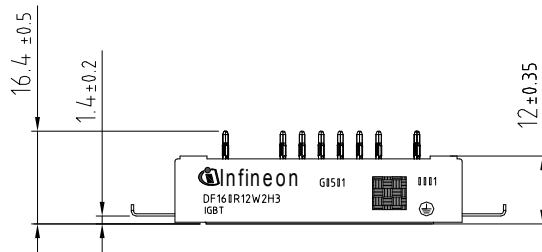
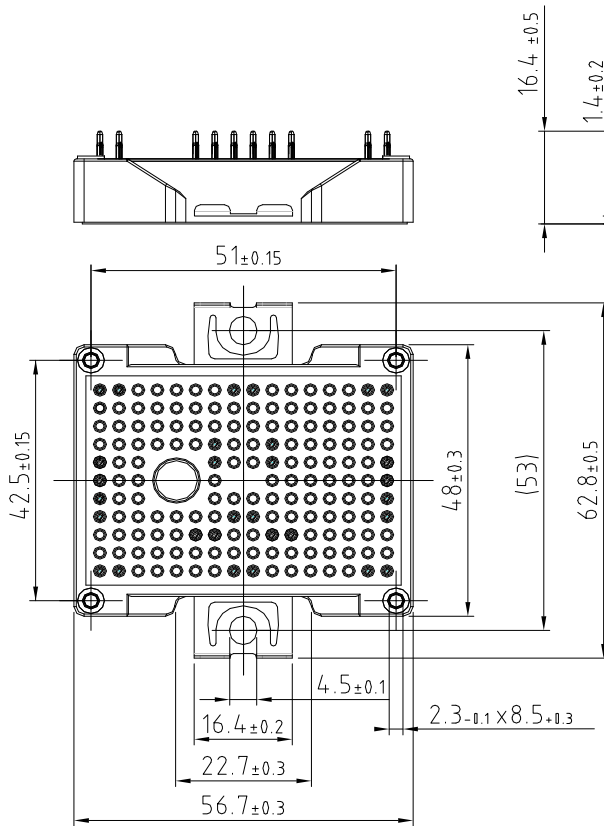
NTC-サーミスタ サーミスタの温度特性
 NTC-Thermistor-temperature characteristic (typical)
 $R = f(T)$



回路図 / Circuit diagram



パッケージ概要 / Package outlines



- Pin-Grid 3.2mm
- Tolerance of PCB hole pattern $\varnothing 0.1$
- Hole specification for contacts see AN 2009-01:
Diameters of drill $\varnothing 1.15\text{mm}$
and copper thickness in hole 25-50 μm

